Contact Name Title - Contact Phone - Contact* Product-Env-Stewards Authorized Representative* Product-Env-Stewards Product Enviro Compliance Authorized Representative* Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product Enviro Compliance Phone - Representative* Phone - Representative* Phone - Representative* Phone - Representative* Product-Env-Stewards Produc	IPC - ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
Company name* Company unique ID Unique ID Authority Response Date* 2024-04-25 Contact Name Title - Contact Product Enviso Compliance Interpolate Envisor Compliance NA Product Envisor Stewards @onsemi.com Manufacturing Site Weight* UOM U Annufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Plating / Grid Array Material Terminal Base Alloy NA Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy NA 0 C 30 Seconds 3	752-21.1					*						als and Mi	fg Informatio	on		
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Title - Representative Phone - Representative Phone - Representative Product Enviro Compliance NA Product Enviro Compliance NA Product-Env-Stewards © onsemi.com Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM U HUF75345P3 FET 55V 7.0 mOhm TO220 2024-04-25 CNC 2030.181 mg E Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Mate Tin (Sn) - annealed CU Alloy NA 0 C 30 seconds 3	ontact Name			Title - Contact			I	Phone - Contact*					Email - Contact*			
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Requester Item Number	Authorized Representative*			Title - Representative			I	Phone - Representative*				Email - Representative*				
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	omments															
or more information regarding material composition please refer to page 3			•.•													

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominal contains a RoHS restricted substance inexcess encompass all such components. Supplier certi as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided by certification in this paragraph. If the Company	ted biphenyls and/or polybrominated dipheny of an applicable quantity limit, please indicate fies that it gathered the information it provident. Supplier acknowledges that Company will we relied on information provided by others in the supplier agrees that, at a minimum and the Supplier enter into a written agreements ource of the Supplier's liability and the Com-	2011/65/EU and implemented by the laws of the End ethers (each a "RoHS restricted substance") in except the below which, if any, RoHS exemption you believe in this form using appropriate methods to ensure rely on this certification in determining the compliant completing this form, and that Supplier may not have its suppliers have provided certifications regarding ent with respect to the identified part, the terms and capany's remedies for issues that arise regarding information in the content of the content is the content of	sess of the applicable quantity limit identified ab we may apply. If the part is an assembly with low its accuracy and that such information is true an- nce of its products with European Union member ave independently verified such information. Ho their contributions to the part, and those certification conditions of that agreement, including any warr	bove. If a homogeneous material within the part ver level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. It is involved in situations where Supplier has not ations are at least as comprehensive as the ranty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temper	erature type solders (i.e. lead based solder	alloys containing 85% by weight or more lead).								
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.81	mg	Supplier	Silicon (Si)	7440-21-3		2.81	mg
Die Attach Solder	1.111	mg	Supplier	Silver (Ag)	7440-22-4		0.0278	mg
			A	Lead (Pb)	7439-92-1	7a	1.0277	mg
			Supplier	Tin (Sn)	7440-31-5		0.0555	mg
Lead Frame	1492.12		В	Nickel (Ni)	7440-02-0		0.1492	mg
			Supplier	Iron (Fe)	7439-89-6		1.4921	mg
			Supplier	Copper (Cu)	7440-50-8		1490.031	mg
			Supplier	Phosphorus (P)	7723-14-0		0.4476	mg
Mold Compound-Black	518.4	mg		Proprietary	proprietary data		25.92	mg
			Supplier	Carbon Black (C)	1333-86-4		2.592	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		386.208	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		77.76	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		25.92	mg
Plating	13.3	mg	Supplier	Tin (Sn)	7440-31-5		13.3	mg
Wire Bond - Al	2.44	mg	Supplier	Aluminum (Al)	7429-90-5		2.44	mg